

AMENDMENT TO THE CLAIMS

The following claim listing replaces all prior listings and versions of the claims:

LISTING OF CLAIMS

1. (Currently Amended) A method of orienting an electronic functional material, the method comprising:

a mixed material preparation step of preparing a mixed material from an electronic functional material and a matrix material used for orientating the electronic functional material;

an orientation step of orientating the mixed material; and

a matrix material removal step of removing the matrix material from the mixed material which has been oriented,

wherein [[, in]] the matrix material removal step includes:

an irradiation step of irradiating an ultraviolet ray to the mixed material followed by a removing step of removing the matrix material by heating or etching. ~~, the matrix material is removed by at least either heating or etching.~~
2. (Original) The method of orienting an electronic functional material according to claim 1, wherein the electronic functional material contains an organic semiconductor compound.
3. (Original) The method of orienting an electronic functional material according to claim 1, wherein the electronic functional material contains nanotubes.

4. (Original) The method of orienting an electronic functional material according to claim 1, wherein the mixed material preparation step includes a mixed material layer formation step of forming a mixed material layer containing the mixed material.

5. (Previously Presented) The method of orienting an electronic functional material according to claim 1, wherein, in the orientation step, the mixed material is oriented by at least either drawing or shear deformation.

6. (Cancelled)

7. (Previously Presented) The method of orienting an electronic functional material according to claim 1, wherein the matrix material contains a heat developable type resist material which is sublimated and developed by heating after exposed to ultraviolet rays or irradiated with an electronic beam.

8. (Original) The method of orienting an electronic functional material according to claim 1, wherein the matrix material contains a photosensitive polyphthalaldehyde base material.

9. (Original) A method of fabricating an electronic functional material thin film by use of the electronic functional material orientation method of claim 1.

10. (Original) A method of fabricating a thin-film transistor, wherein an electronic functional material thin film that constitutes a semiconductor layer is formed by the electronic functional material thin film fabricating method of claim 9.

11. (Original) An electronic functional material thin film produced by the electronic functional material thin film fabricating method of claim 9.

12. (Original) A thin-film transistor having a semiconductor layer composed of the electronic functional material thin film of claim 11.

13. (Previously Presented) The method of orienting an electronic functional material according to claim 2, wherein the organic semiconductor compound is selected from the group consisting of pentacene, tetracene, thiophene oligomer derivatives, phenylene derivatives, phthalocyanine compounds, polyacetylene derivatives, polythiophene derivatives and cyanine dye.

14. (Previously Presented) The method of orienting an electronic functional material according to claim 1, wherein, in the orientation step, the mixed material is oriented by liquid crystal orientation.

15. (Previously Presented) The method of orienting an electronic functional material according to claim 1, wherein, in the matrix material removal step, the matrix material is

removed through sublimation or evaporation by at least any of heating, light and depressurization.

16. (New) The method of orienting an electronic functional material according to claim 1, wherein the irradiation of the ultraviolet ray in the irradiation step and the heating in the removing step monomerize and heat-sublime the matrix material to remove the matrix material from the mixed material.